

# **High Voltage MOSFET**

**IXTP 01N100D** 

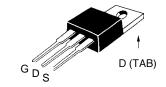
N-Channel, Depletion Mode

 $V_{DSS} = 1000 \text{ V}$   $I_{D25} = 100 \text{ mA}$   $R_{DS(on)} = 110 \Omega$ 



Symbol	<b>Test Conditions</b>	Maximum Ratings	
V <sub>DSS</sub>	$T_J = 25^{\circ}C \text{ to } 150^{\circ}C$	1000	V
$\mathbf{V}_{DGR}$	$T_{_{\rm J}} = 25^{\circ}\text{C} \text{ to } 150^{\circ}\text{C}; R_{_{\rm GS}} = 1 \text{ M}\Omega$	1000	V
$\overline{\mathbf{V}_{GS}}$	Continuous	±20	V
$V_{\rm GSM}$	Transient	±30	V
I <sub>D25</sub>	$T_{c} = 25^{\circ}C; T_{J} = 25^{\circ}C \text{ to } 150^{\circ}C$	100	mA
I <sub>DM</sub>	$T_{\rm C}$ = 25°C, pulse width limited by $T_{\rm J}$	400	mA
P <sub>D</sub>	$T_{c} = 25^{\circ}C$ $T_{A} = 25^{\circ}C$	25 1.1	W
	^	-55 +150	°C
$T_{JM}$		150	°C
$T_{stg}$		-55 <b>+</b> 150	°C
T <sub>L</sub>	1.6 mm (0.063 in.) from case for 10 s	300	°C
Weight		1	g

## TO-220AB (IXTP)



#### **Features**

- Normally ON mode
- $^{\bullet}$  Low  $\mathsf{R}_{\scriptscriptstyle{\mathsf{DS}\;(\mathsf{on})}}$  HDMOSTM process
- Rugged polysilicon gate cell structure
- Fast switching speed

# **Applications**

- Level shifting
- Triggers
- Solid state relays
- Current regulators

Symbol	<b>Test Conditions</b>	$(T_J = 25^{\circ}C, \text{ unless } C)$ min.		istic Va se speci max.	
V <sub>DSS</sub>	$V_{GS} = -10 \text{ V}, I_{D} = 25 \mu\text{A}$	1000			V
$V_{_{GS(off)}}$	$V_{DS} = 25V, I_{D} = 25 \mu A$	-2.5		-5	V
I <sub>GSS</sub>	$V_{GS} = \pm 20 V_{DC}, V_{DS} = 0$			±100	nA
DSS(off)		T <sub>J</sub> = 25°C T <sub>J</sub> = 125°C		10 250	μA μA
R <sub>DS(on)</sub>	$V_{GS} = 0 \text{ V}, I_D = 50 \text{ mA Note}$	÷ 1	90	110	Ω
D(on)	$V_{GS} = 0 \text{ V}, V_{DS} = 50 \text{V Note}$	<del>)</del> 1	250		mΑ

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#### **Symbol Test Conditions Characteristic Values** $(T_J = 25^{\circ}C, \text{ unless otherwise specified})$ min. typ. max. $V_{DS} = 50 \text{ V}; I_{D} = I_{D25}$ Note 1 100 150 mS $\boldsymbol{g}_{\text{fs}}$ 120 $\mathbf{C}_{\mathrm{iss}}$ рF $V_{GS} = -10 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$ $\mathbf{C}_{\mathrm{oss}}$ 15 рF рF 3 $C_{rss}$ 8 t<sub>d(on)</sub> ns $V_{_{QS}} = 0 \text{ V, to } -10 \text{ V, } I_{_{D}} = 50 \text{ mA}$ 6 t, ns

### Source-Drain Diode

t<sub>d(off)</sub>

 $\overline{R}_{\underline{\text{thJC}}}$ 

t,

Characteristic Values (T, = 25°C, unless otherwise specified)

30

51

ns

ns

K/W

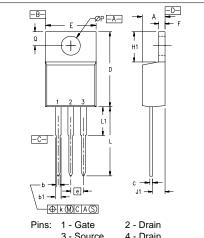
Symbol	Test Conditions min.		max.	,
V <sub>SD</sub>	$V_{GS} = -10 \text{ V}, I_F = I_{D25}$ Note 1	1.0	1.5	V
t <sub>rr</sub>	$I_F = 0.75 \text{ A}, -di/dt = 10 \text{ A/}\mu\text{s}, $ $V_{DS} = 25 \text{ V}, V_{GS} = -10 \text{V}$		1.5	μs

Note 1: Pulse test,  $t \le 300 \mu s$ , duty cycle  $d \le 2 \%$ 

 $V_{ds} = 100 V$ 

 $R_c = 30\Omega$ , (External)

#### **TO-220 AD Dimensions**



:	1 - Gate	2 - Drain
	3 - Source	4 - Drain
		Bottom Side

MYZ	INCHES		MILLIMETERS		
2114	MIN	MAX	MIN	MAX	
Α	.170	.190	4.32	4.83	
Ь	.025	.040	0.64	1.02	
b1	.045	.065	1.15	1.65	
С	.014	.022	0.35	0.56	
D	.580	.630	14.73	16.00	
E	.390	.420	9.91	10.66	
е	.100 BSC		2.54 BSC		
F	.045	.055	1.14 1.40		
H1	.230	.270	5.85	6.85	
J1	.090	.110	2.29	2.79	
k	0	.015	0	0.38	
L	.500	.550	12.70	13.97	
L1	.110	.230	2.79	5.84	
ØΡ	.139	.161	3.53	4.08	
0	.100	.125	2.54	3.18	